

产品规格书

Product Specification



光MOS固态继电器

OPTOCOUPLER

MT-AQY221R2S

SOLID STATE RELAY

晶体管光耦

可控硅光耦

达林顿光耦

高速光耦

施密特触发器

IPM驱动光耦

光MOS固态继电器

IGBT驱动光耦

深圳市美特光电子有限公司

SHENZHEN MATELIGHT ELECTRONICS CO.,LTD

www.matelight.cn Q

1 概述 General

产品 MT-AQY221R2S由砷化铝镓红外发光二极管作为输入级耦合到高电压输出光探测电路。光探测电路由高速光电二极管阵列和驱动电路构成，用以开启/关断两个独立的高压金属氧化物半导体场效应管 (MOSFET)。一个最小 5mA 的电流流经输入级红外发光二极管可确保继电器动作。当加在输入级红外发光二极管的正向压降为 0.8V 或更小值时，继电器可确保复位。产品见图 1。



图 1 产品 Figure 1-Product

The MT-AQY221R2S consists of a AlGaAs infrared emitting diode input stage optically coupled to a high-voltage output detector circuit. The detector consists of a high-speed photovoltaic diode array and driver circuitry to switch on/off two discrete high voltage MOSFETs. The relay action with a minimum input current of 5mA through the input LED. The relay reset with an input voltage of 0.8V or less. Products shown in Figure 1.

2 特点 Features

- 微型光 MOS 固态继电器。Micro Photo MOSFET Solid State Relay.
- 单通道常开型单刀单掷继电器。Single Channel Normally On Single-Pole-Single-Throw (SPST) Relay.
- 400V 输出耐压产品。400V Output Withstand Voltage.
- 100mA 额定电流产品。100mA Current Rating.
- 低输入电流，CMOS 兼容。Low Input Current: CMOS Compatibility.
- 非常快的开关速度：典型值 0.5ms (Ton), 0.2ms (Toff)。
High Speed Switching: 0.5ms (Ton), 0.2ms (Toff) Typical
- 高输入输出绝缘耐压：3750 Vrms for 1 min.
High Input-to-Output Insulation Voltage: 3750 Vrms for 1 min.

3 应用 Applications

- 电信切换。Telecommunication Switching.
- 数据通讯。Data Communications.
- 电池管理。Battery Management.
- 工业控制。Industrial Controls.
- 医疗设备。Medical Equipment.
- EMR/机械继电器替代。EMR / Reed Relay Replacement.

4 电原理图 Schematic Diagram

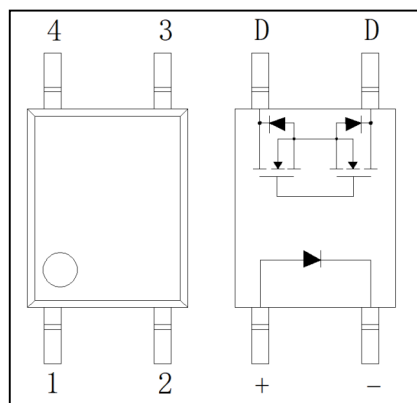


图 2 电原理图 Figure 2-Schematic

5 极限参数 Absolute Maximum Ratings

表 1 极限参数

Table 1-Absolute Maximum Ratings

参数名称 Characteristic		符号 Symbol	额定值 Rating	单位 Unit
输入端 Input	正向电流 Forward Current	I_F	25	mA
	反向电压 Reverse Voltage	V_R	5	V
	耗散功率 Power Dissipation	P_M	50	mW
输出端 output	开关电压 Switching Voltage	$V_{O(MAX)}$	400	V
	连续通态电流 Continuous load current	$I_{O(MAX)}$	100	mA
	耗散功率 Power dissipation	P_C	200	mW
工作温度 Operating temp.		T_{aop}	-40 ~ +105	°C
贮存温度 Storage temp.		T_{stg}	-55 ~ +125	°C
焊接温度 Soldering Temperature (10 Sec max.)		T_{sld}	255	°C
绝缘电压 Isolation voltage (RH≤60%,交流 1 分钟) (RH≤60%, AC 1min.)		V_{ISO}	3750	V_{rms}

6 光电参数 Opto-Electrical Characteristics

表 2 光电参数

Table 2-Opto-Electrical Characteristics

$T_a=25^{\circ}\text{C}$

参数名称 Characteristic	符号 Symbol	测试条件 Test conditions	最小值 Min.	典型值 Typ.	最大值 Max.	单位 Unit
输入端 Input	正向电压 Forward voltage	V_F	$I_F=10\text{mA}$	1.2	1.4	V
	反向电流 Reverse current	I_R	$V_R=5\text{V}$		10	uA
	动作电流 Action Current	$I_{F(ON)}^a$	$I_O=100\text{mA}$	2	3	mA
	复位电流 Reset Current	$I_{F(OFF)}$	$I_O=100\text{mA}$	0.35	0.5	mA
输出端 Output	断态漏电流 OFF-State Leakage Current	I_{OFF}	$V_O=400\text{V}$		1	uA
	导通电阻 ON Resistance	R_{ON}	$I_O=100\text{mA}, I_F=5\text{mA}$		30	Ω
	输出电容 Output Capacitance	C_O	$V_{OFF}=0\text{V},$ $f_O=1\text{MHz}$	500		pF
传输 Xfer	动作时间 Action Time	T_{ON}	$I_F=10\text{mA}, I_O=100\text{mA}$		0.5	ms

	复位时间 Reset Time	T_{OFF}	$I_F=10\text{mA}, I_O=100\text{mA}$			0.2	ms
	耦合电容 Coupled Capacitance	$C_{I/O}$	$V_s=0, f=1\text{MHz}$		0.5		pF
隔离 Isolation	绝缘电压 Isolation voltage	V_{ISO}	$I_{off}\leq 0.3\text{mA},$ AC, 60s	3750			V

^a 保证所有器件在 I_F 值小于或等于最大的 $I_{F(ON)}$ 时动作。
It is guaranteed that all devices active when I_F value is less than or equal to the maximum value of $I_{F(ON)}$.

7 特性曲线 Performance Curves

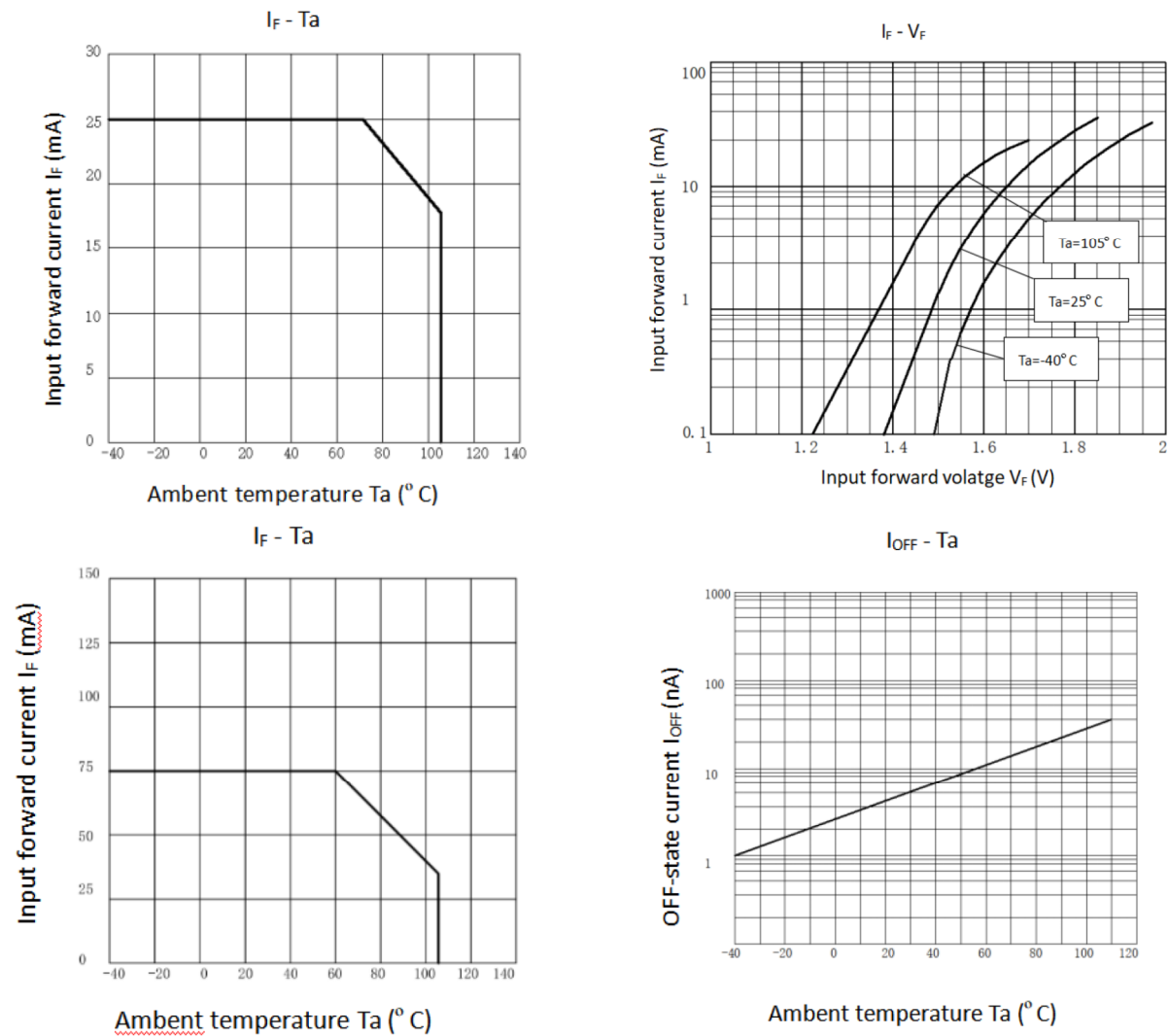


图 3 特性曲线

Figure 3- Performance Curves

8 外形尺寸及电原理图 Dimensions and Circuit Diagram

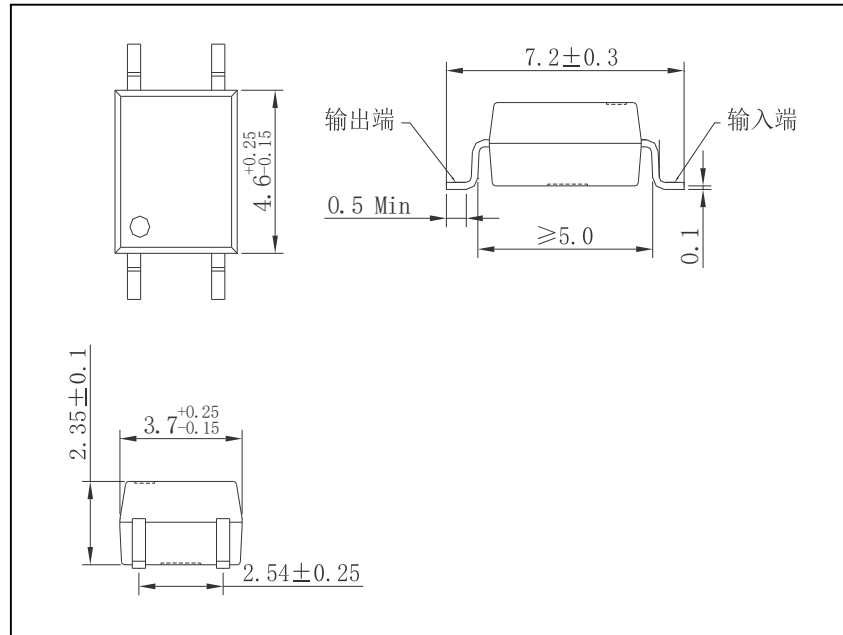


图 4 MT-AQY221R2S 外形尺寸

Figure 4- The dimensions of MT-AQY221R2S

9 标志 Mark

产品上应有型号、公司商标、生产日期代码、引出端识别标记。例如：MT-AQY221R2S产品印章如图5。

Print type characters ,trade mark and Lot.No.on the Photo Coupler.For example the marking of product MT-AQY221R2Sis shown as figure 5.

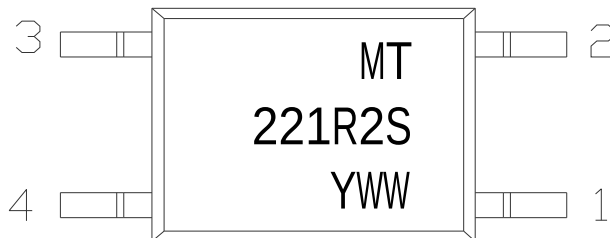


图 5 产品印章

Figure 5- Marking

10 包装方式 Packing

10.1 编带包装 (Tape and reel): 适用于 For MT-AQY221R2S

10.1.1 每卷数量 (Qty/reel): 3000 只 (pcs)。每箱数量 (Qty/ctn): 45000 只 (pcs)。

10.1.2 内包装 (Inner packing):

每卷盘 3000 只, 贴合格证 (型号、生产日期代号、检验员代号)。

3000pcs/reel, certificate on reel (model, code of product date, Inspector's code)

10.1.3 外包装(Outter packing):

公司名称、地址、商标、产品型号、数量等标志。

Indication of company name, address, trade mark, model and quantity.

10.1.4 示意图 (Schematic):

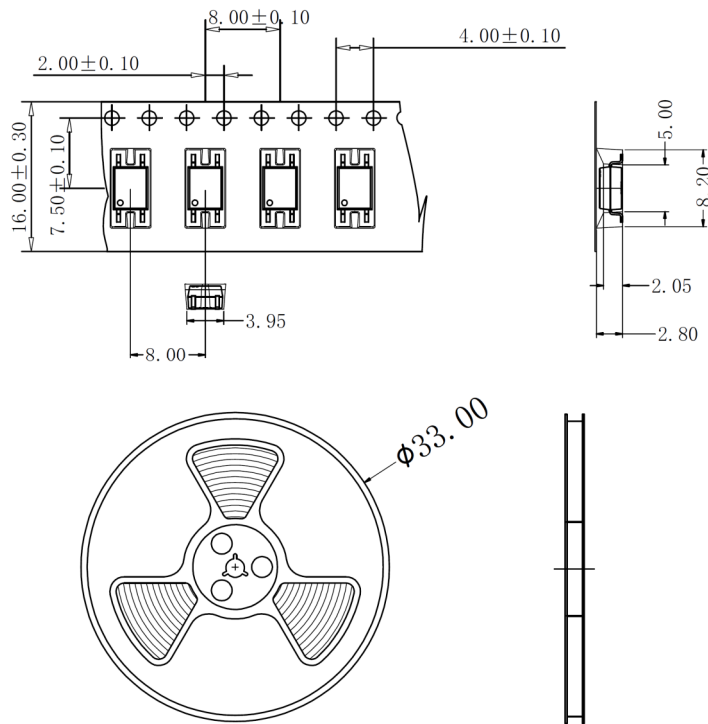


图 6 编带包装示意图

Figure 6- Taping Packing Schematic

10.2 标识 Label

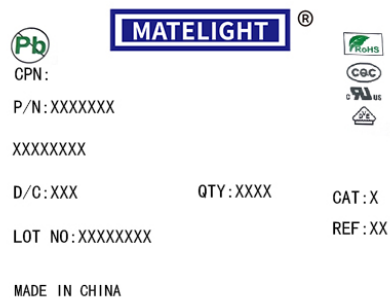


图 7 标识

Figure 7-Label

10.3 注意事项 Note

10.3.1 推荐贮存温度 Recommend storage Temp.: 0~40°C;

推荐贮存湿度 Recommend storage humidity: <70%;

贮存有效期半年 Storage life: Half of a year.

10.3.2 湿气敏感度等级 3 级。MSL level: MSL 3.

10.4 引脚镀锡厚度: 大于等于 5μm。

Thickness of Sn which plated on lead frame: ≥5 μm.

10.5 推荐焊接条件 Recommended soldering conditions

10.5.1 施加在环氧树脂上的温度不要超过最高贮存温度。

Not to apply high temperature exceeding the maximum storage temperature to the epoxy resin.

10.5.2 在高温下不要对环氧树脂施加压力。

Not to apply any force to the epoxy resin at high temperature.

10.5.3 焊接过程 Soldering process

1、在焊接过程中不要对器件施加任何压力。

Not to apply any stress to the component during the soldering process.

2、回流焊 Reflow soldering

1) 推荐锡膏规格 Recommend tin glue specifications:

a) 熔点 Melting temperature: 217°C

b) 组分 Contains: SnAg3Cu0.5

2) 回流焊工序必须在器件冷却至室温后进行。Never take next process until the component is cooled down to room temperature after reflow.

3) 推荐回流焊接参数，如下图所示： The recommended reflow soldering profile is following:

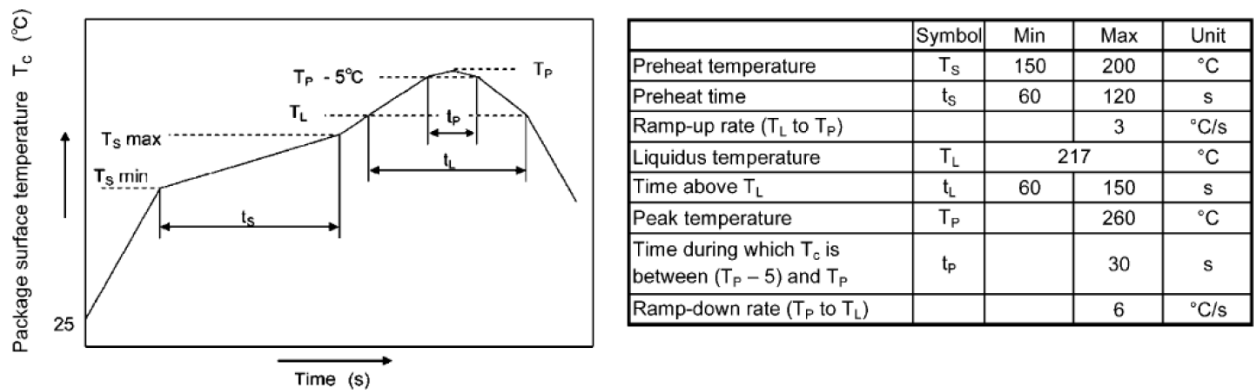


图 8 回流焊参数

Figure 8-Recommended reflow soldering profile